ABSTRACT OF THE DISCLOSURE

In order to realize a fan-in and fan-out semiconductor device having improved reflowing resistance, in which bump electrodes disposed on the outside of a chip are supported with reliability, the semiconductor device comprises: a porous elastomer 3 which is disposed over the principal surface 1a of a semiconductor chip 1 and in which an opening 3c for exposing an electrode pad 1b on the semiconductor chip 1 is formed; a tape substrate 4 which is provided with a lead 4c extending from the principal surface 1a of the semiconductor chip 1 to the outside, whose one end is electrically connected to the electrode pad 1b and whose other end is electrically connected to a bump electrode 2, and in which an opening 4e for exposing the electrode pad 1b is formed; a frame-shaped reinforcing member 6 for reinforcing the support for the bump electrode 2 disposed on the outside of the semiconductor chip 1; and a sealing portion 5 for sealing the electrode pad 1b of the semiconductor chip 1 and the lead 4c. The support by the tape substrate 4 for the bump electrode 2 disposed on the outside of the semiconductor chip 1 is reinforced by the reinforcing member 6.

This Sheet Has Been Replaced

